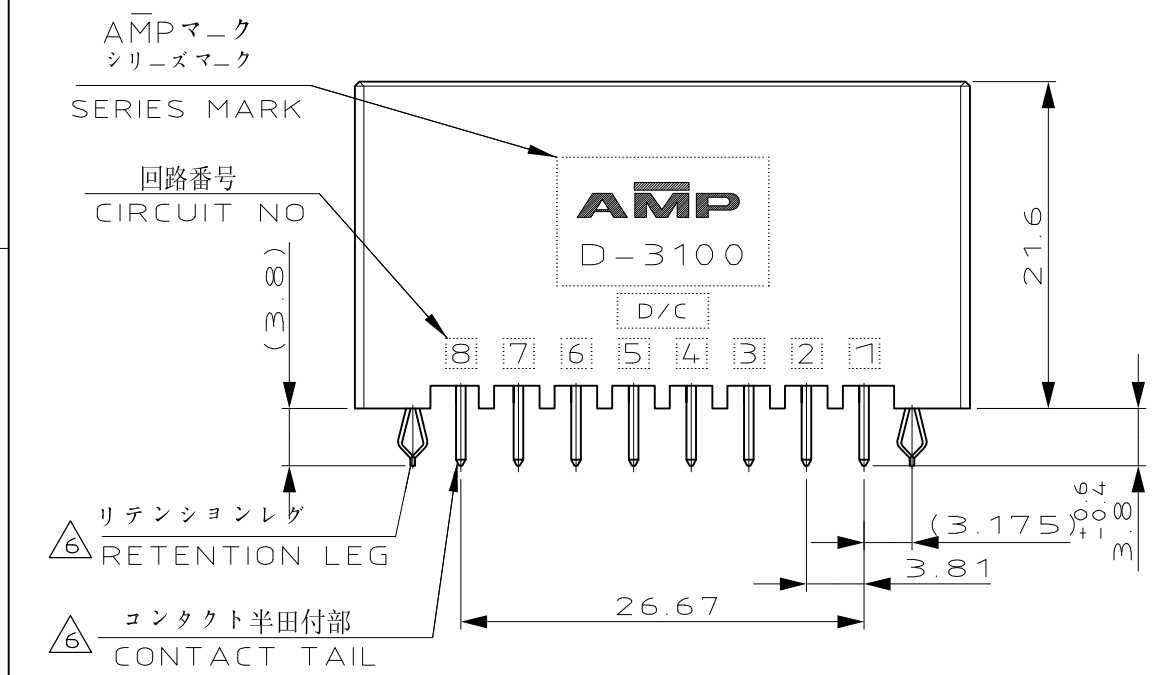
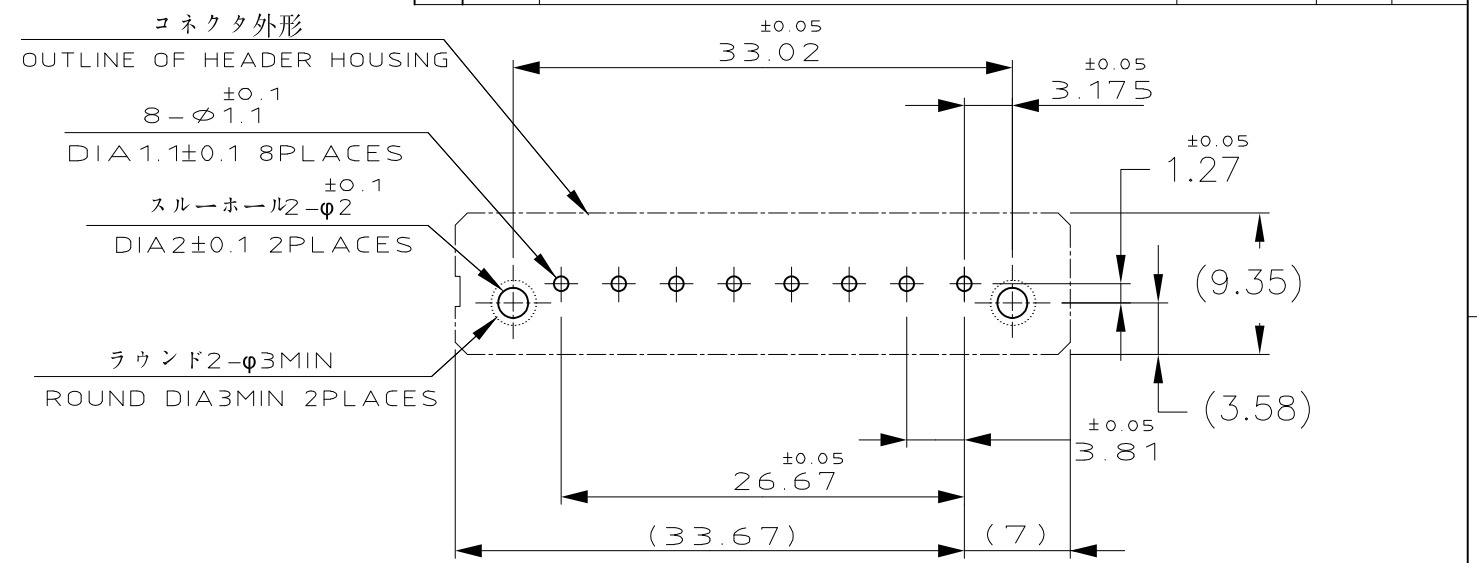
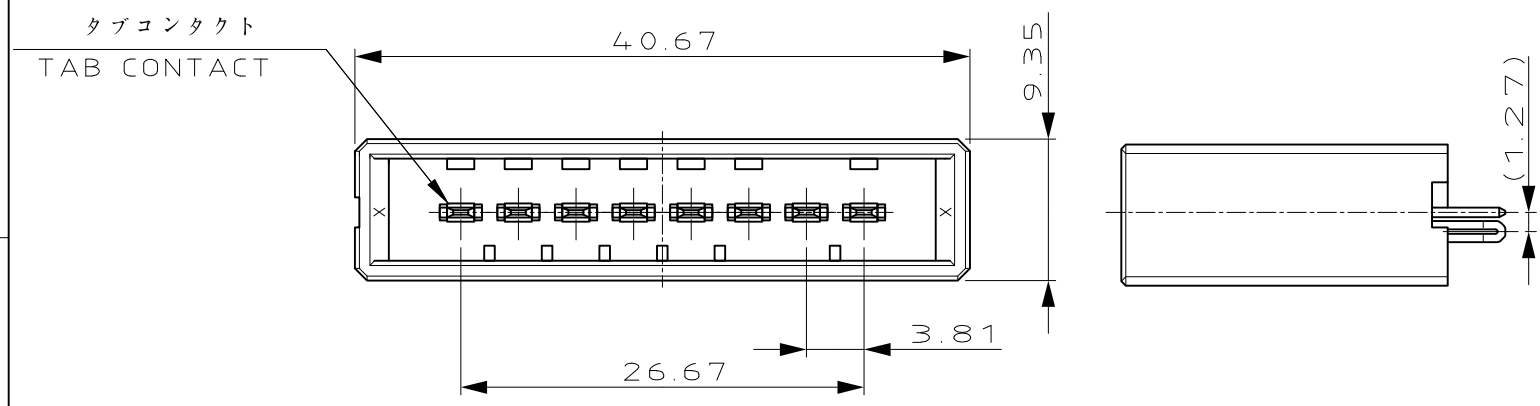


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LOC	DIST	REVISIONS					
J	-	P	LTR	DESCRIPTION	DATE	DWN	APVD
		F		REVISED	04JUL2012	H.M	N.Y



推奨基板取付け穴寸法
 PC 基板厚: 1.6 ± 0.1
 (非累積公差)
 (コネクタ搭載面)

RECOMEND PC BOARD HOLE PATTERN
 PC BOARD THICKNESS: 1.6 ± 0.1
 (NOT ACCUMULATE TOLERANCE)
 (CONNECTOR MOUNT SIDE)

NOTES

- MATERIAL: HOUSING: GLASS FILLED THERMO PLASTIC, POLYESTER (94V-0), COLOR: BLACK
 CONTACT: COPPER ALLOY
 RETENTION LEG: COPPER ALLOY
- FINISH (CONTACT AREA): 0.38 μm MIN GOLD PLATING OVER Ni PLATING
- FINISH (CONTACT AREA): 0.76 μm MIN GOLD PLATING OVER Ni PLATING
- FINISH (CONTACT AREA): 2.0 μm MIN TIN PLATED OVER NICKEL
- FINISH (RETENTION LEG): TIN-LEAD PLATED (CONTACT TAIL) OVER NICKEL
- FINISH (RETENTION LEG): TIN PLATED (CONTACT TAIL) OVER NICKEL

注記

- 材料: ハウジング: ガラス入り熱可塑性ポリエステル樹脂 (94V-0), 色: 黒
 コンタクト: 銅合金
 リテンションレグ: 銅合金
- めっき: コンタクト全面 Ni 下地
 接触部 0.38 μm MIN 金めっき
- めっき: コンタクト全面 Ni 下地
 接触部 0.76 μm MIN 金めっき
- めっき: コンタクト全面 Ni 下地
 接触部 2.0 μm MIN スズめっき
- めっき: リテンションレグとコンタクト半田付部
 ニッケル下地の土に半田めっき
- めっき: リテンションレグとコンタクト半田付部
 ニッケル下地の土にスズめっき

△6	△4	1-178317-5
△6	△3	1-178317-3
△6	△2	1-178317-2
(FINISH)		製品番号 (PART NO.)

THIS DRAWING IS A CONTROLLED DOCUMENT.		DWN	N.MATSUBARA	19APR1994	STE TE Connectivity
		CHK	S.MANABE	20APR1994	
		APVD	S.MANABE	20APR1994	
		PRODUCT SPEC			
DIMENSIONS:	TOLERANCES UNLESS OTHERWISE SPECIFIED:	NAME			
mm	0 PLC ±	8 POS SINGLE ROW VERTICAL HDR ASSY FOR DYNAMIC D-3100			
	1 PLC ±				
	2 PLC ± ^{10>} ±0.3				
	3 PLC ± ^{10< 30} ±0.4				
	4 PLC ± ^{30< 100} ±0.45	APPLICATION SPEC			
MATERIAL	FINISH	WEIGHT	SIZE		RESTRICTED TO
SEE NOTE	SEE NOTE		A3 00779 C-178317		-
CUSTOMER DRAWING			SCALE	SHEET	REV
			2:1	1 OF 1	F